

IEEE Electromagnetic Compatibility Society

Application to the Financial Assistance Program (FAP) for Economically Disadvantaged Engineers (EDE)

The IEEE EMC Society provides funding to selected economically disadvantaged engineers from both developing and developed countries to attend the IEEE International Symposium on EMC (ISEMC). The following are the requirements and conditions that must be met to be eligible to apply for financial assistance:

1. The applicant must be a presenter at ISEMC with either a technical paper or participation in a workshop, tutorial, or demonstration that provides significant value to the symposium. If there are multiple authors or presenters of a paper or other presentation, only one may apply for financial assistance. The recipient(s) must be pre-registered as proof of commitment to participate at the ISEMC, and must attend the Symposium to receive reimbursement. No funds are to be provided in advance of the Symposium to the recipient(s).
2. The minimum reimbursement amount is the cost of the basic registration fee, but not to exceed the sum requested by the applicant if less than the registration fee amount is requested. At no time shall funds be paid in advance. Hardship situations shall be considered on a case by case basis, as necessary.
3. Requests for additional financial assistance to cover travel and/or lodging will be considered on a funds-available basis. If financial assistance for travel and/or lodging costs is authorized by the FAP/EDE Committee, the recipient must pay for these expenses and will be reimbursed only when receipts are provided as part of an IEEE Expense Report, which must be submitted for reimbursement.
4. The applicant must provide a written endorsement or letter of support from both a co-worker/supervisor and from an official of their Regional/Section/Local IEEE (Chairman, Vice Chair, Chapter Chair, etc)
5. The applicant must also provide a statement of commitment to participate at the ISEMC in addition to a statement that they will support their IEEE Section or EMC Chapter by presenting their paper or other elements of their participation at ISEMC to fellow engineers at the local or regional level.

Applications will be assessed by the (FAP/EDE) committee. The committee will take into account the technical merit of the presentation(s) and if participation provides a substantial contribution to the symposium, and the timely submittal of this application. The decision of the committee on their application/request will be sent to each applicant. Basic financial support will be limited to symposium registration (excluding optional activities and services). The applicant may also request financial assistance to cover travel and/or lodging. The FAP/EDE committee shall determine the extent of financial assistance to be provided.

Applications must be received by April 1 of the calendar year by the IEEE EMC Board of Directors FAP/EDE Committee (address below). Please provide the following support documentation consisting of: (1): A completed application form including the signed endorsement/support form on the following two pages and (2): a copy of the submitted paper, proposal or technical presentation.

IEEE EMCS FAP/EDE, 1210 Lawn Meadow Lane, Naperville, IL 60540-6248 USA

For more information about the FAP/EDE program, please visit: www.emcs.org.

Application to the Financial Assistance Program for Economic Disadvantaged Engineers

I am applying for financial assistance to attend the IEEE International Symposium on EMC.

Year:	Symposium Location:	
Name: (Prof./Dr./Mr./Mrs./Ms):		
Place of Employment:		
Institution/Department:		
Postal Address (Street):		
City:	Province/State:	
Country:	Postal Code:	
E-mail:	Phone Number:	

Please send all correspondence to my business above home address, below

Postal Address (Street):		
City:	Province/State:	
Country:	Postal Code:	
E-mail:	Phone Number:	
Academic/professional qualifications, with date(s) obtained:		
Title of Paper, Tutorial, Workshop or Proposal:		
Authors/Co-Authors and Affiliation:		
Describe economic disadvantage:		
Registration Fee: (USD) \$	Projected Transportation: (USD) \$	Projected Hotel: (USD) \$

I agree to participate in the IEEE International Symposium on EMC and to also make my presentation available to regional/local IEEE organizations.

Date:	Signature:
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Please send this application to: **IEEE EMCS FAP/EDE PROGRAM**
1210 Lawn Meadow Lane, Naperville, Illinois 60540 USA
hrhofmann@att.net

Oct 21, 2007

Endorsement to the IEEE EMCS Financial Assistance Program for Economic Disadvantaged Engineer

Year:	Symposium Location:
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Applicant's Name: (Prof./Dr./Mr./Mrs./Ms):
Title of Paper, Tutorial, Workshop or Proposal:
Authors/Co-Authors and Affiliation:

I support the application for economic disadvantaged engineers grant to enable the person (named above) to attend the IEEE International Symposium on EMC for the following reasons:

Name: (Prof./Dr./Mr./Mrs./Ms):	
Place of Employment:	
Position/Title:	
Postal Address (Street):	
City:	Province/State:
Country:	Postal Code:
E-mail:	Phone Number:

<u>Type of Endorsement</u>
Co-worker/Supervisor: (Yes/No):
IEEE EMCS Director (Yes/No):
Regional/local IEEE Officer (Section Chairman, Vice-Chairman, Chapter Chair, etc) (Yes/No)

Date:	Signature:
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Please send this endorsement to:

IEEE EMCS FAP/EDE PROGRAM
1210 Lawn Meadow Lane
Naperville, Illinois 60540 USA
hrhofmann@att.net